



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



- **Steep Roll-off Filter for 915 MHz ISM band**
- **Differential Input / Single-ended Output**
- **Complies with Directive 2002/95/EC (RoHS)**

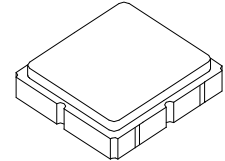


Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	+15	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	

SF2093E

**915.00 MHz
SAW Filter**



SM3030-8

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			915.00		MHz
Insertion Loss, 902 to 928 MHz	IL			2.5	3.5	dB
Amplitude Ripple, p-p, 902 to 928 MHz				0.5	2.0	
VSWR, 902 to 928 MHz				1.75	2.4	
Attenuation Referenced to 0 dB:						
DC to 800 MHz			40	54		
850 to 870 MHz			35	54		
960 to 1035 MHz			28	36		
1035 to 1500 MHz			40	57		
1500 to 3000 MHz			30	56		
Source Impedance	Z_s			800		Ω
Load Impedance	Z_L			50		Ω

Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint		
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	582, YWWS		
Standard Reel Quantity	Reel Size 7 Inch	500 Pieces/Reel	
	Reel Size 13 Inch	3000 Pieces/Reel	

Electrical Connections

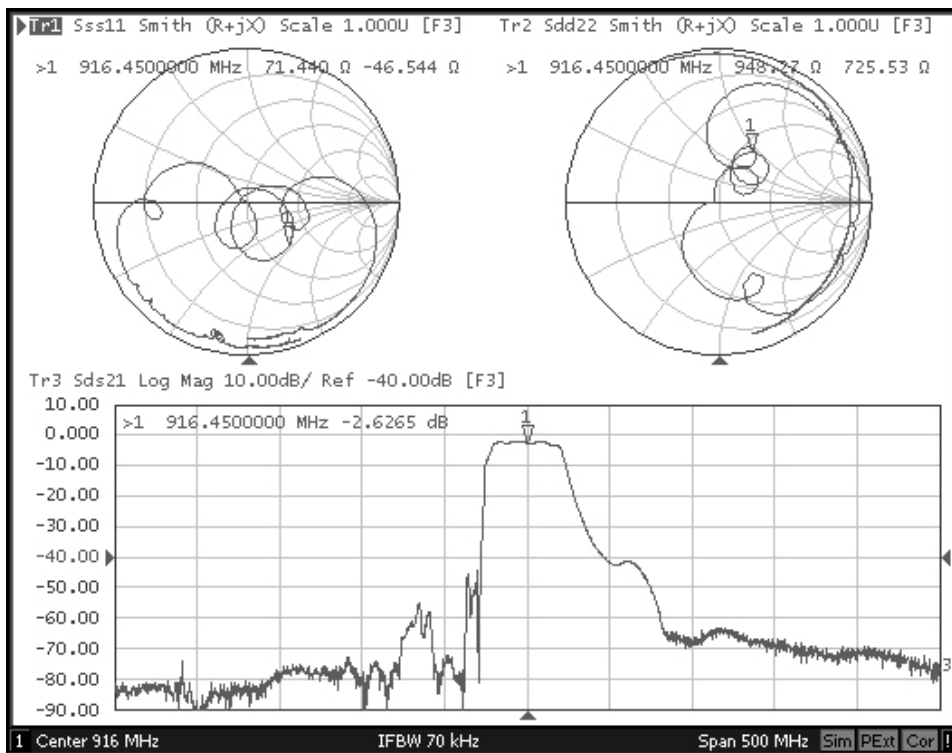
Connection	Terminals
Input, Balanced	1, 3
Output, Single Ended	6
Case Ground	All others

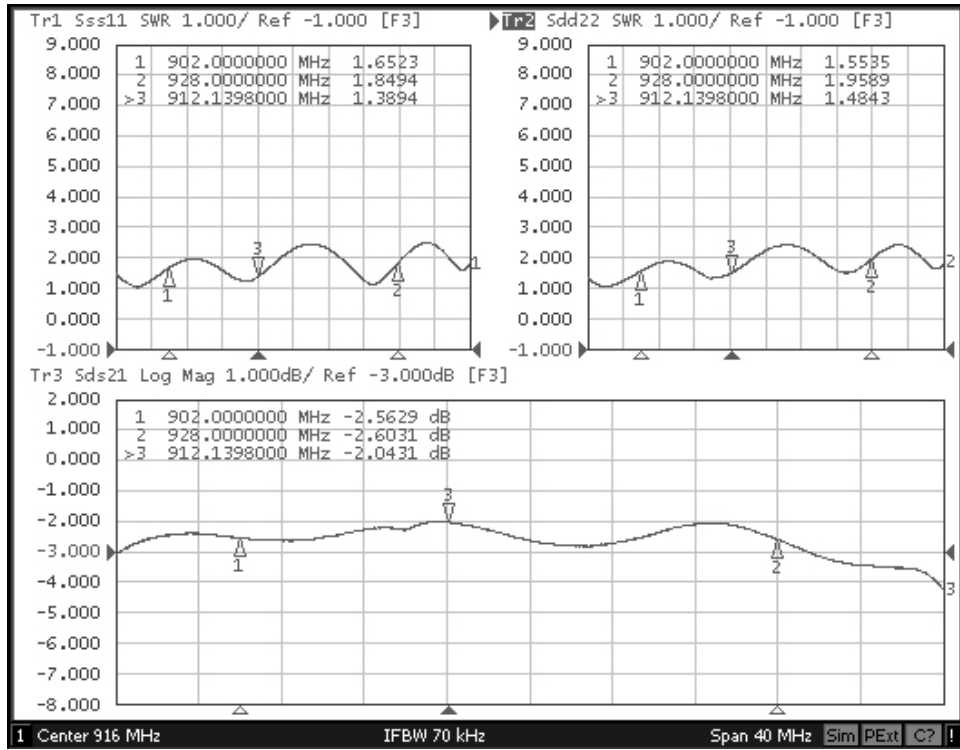
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

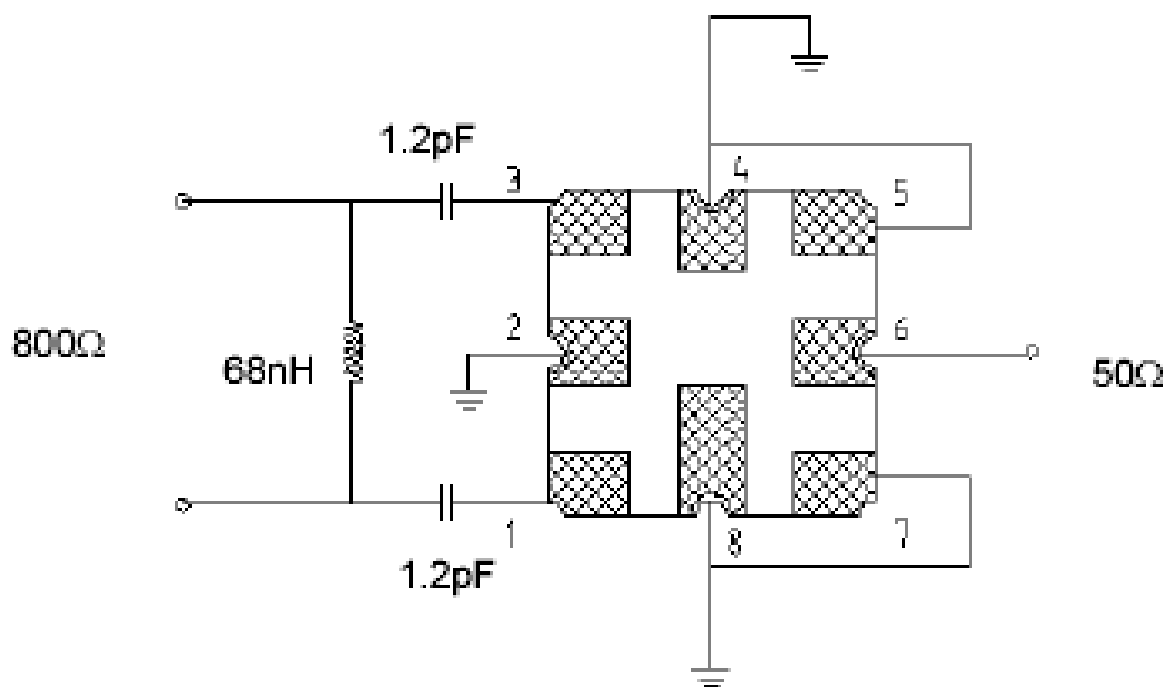
1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_c .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. The design, manufacturing process, and specifications of this filter are subject to change.
5. US and international patents may apply.
6. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

SF2093E Filter Response Plots

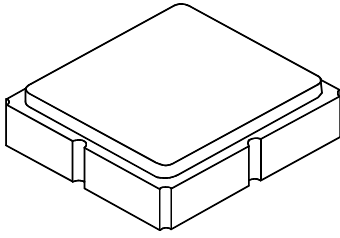




D. MEASUREMENT CIRCUIT:

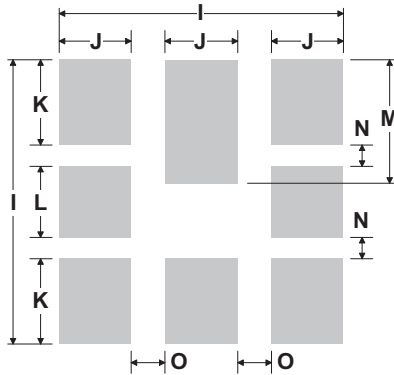


8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.14	1.27	1.40	0.045	0.050	0.055
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	



PCB Footprint Top View

Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
	Pb Free

TOP VIEW

BOTTOM VIEW

